

**RoHS** 

COMPLIANT HALOGEN

Available

## J244-VB Datasheet P-Channel 30-V (D-S) MOSFET

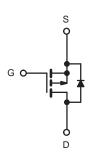
PRODUCT SUMMARY							
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	Q <sub>g</sub> (Typ.)					
- 30	0.050 at V <sub>GS</sub> = - 10 V	- 7.6	13 nC				
- 30	0.056 at V <sub>GS</sub> = - 4.5 V	<del>-</del> 6.0	13110				

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21
  Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> Tested

#### **APPLICATIONS**

- Load Switch
- Battery Switch



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	「 <sub>A</sub> = 25 °C, unless othe	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	- 30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		- 7.6	
Continuous Drain Current (T <sub>1</sub> = 150 °C)	T <sub>C</sub> = 70 °C		- 5.8	
Continuous Drain Current $(T_j = 150 \text{ C})$	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 6.0 <sup>a, b</sup>	
	T <sub>A</sub> = 70 °C		- 5.2 <sup>a, b</sup>	A
Pulsed Drain Current	I <sub>DM</sub>	- 35		
Continuous Courses Drain Diada Current	T <sub>C</sub> = 25 °C		- 3.5	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 2.1 <sup>a, b</sup>	
	T <sub>C</sub> = 25 °C		6.5	
Mauiaum Davies Dissis stics	T <sub>C</sub> = 70 °C		3.5	10/
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2.5 <sup>a, b</sup>	W
	T <sub>A</sub> = 70 °C	1	1.6 <sup>a, b</sup>	
Operating Junction and Storage Temperature Rang	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient <sup>a, c</sup>	t ≤ 10 s	R <sub>thJA</sub>	40	50	°C/W			
Maximum Junction-to-Foot	Steady State	R <sub>thJF</sub>	24	30				

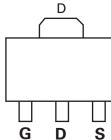
Notes:

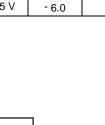
a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 95 °C/W.

d. Package limited.







SPECIFICATIONS T <sub>J</sub> = 25 °C Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Cymbol			Typ.	max.	Onit
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = - 250 μA	- 30			V
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>		00	- 31		
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	l <sub>D</sub> = - 250 μA		4.5		mV/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	- 1.0		- 2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$	1.0		± 100	nA
Cato Course Loanage	-033	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$			- 1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 5	μA
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 20			А
	P	V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 7.0 A		0.050		- Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.6 A		0.056		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 7.0 A		18		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1355		
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 15 V, V <sub>GS</sub> = 0 V, f = 1 MHz		180		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			145		-
Total Gate Charge	Qg	$V_{DS}$ = - 15 V, $V_{GS}$ = - 10 V, $I_{D}$ = - 7.0 A		25	38	nC
Iotal Gale Charge				13	20	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ = - 15 V, $V_{GS}$ = - 4.5 V, $I_{D}$ = - 7.0 A		3.5		
Gate-Drain Charge	Q <sub>gd</sub>			5.5		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2.0	4.0	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 2.7 $\Omega$		13	20	
Turn-Off DelayTime	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ - 5.6 A, $\text{V}_\text{GEN}$ = - 10 V, $\text{R}_\text{g}$ = 1 $\Omega$		23	35	
Fall Time	t <sub>f</sub>			9	18	
Turn-On Delay Time	t <sub>d(on)</sub>			38	57	ns
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 2.7 $\Omega$		89	134	
Turn-Off DelayTime	t <sub>d(off)</sub>	$I_D \cong$ - 5.6 A, $V_{GEN}$ = - 4.5 V, $R_g$ = 1 $\Omega$		22	33	
Fall Time	t <sub>f</sub>			11	17	
Drain-Source Body Diode Characteris	stics					
Continous Source-Drain Diode Current	۱ <sub>S</sub>	T <sub>C</sub> = 25 °C			- 6.5	A
Pulse Diode Forward Current	I <sub>SM</sub>				- 30	
Body Diode Voltage	V <sub>SD</sub>	$I_{S} = -5.6 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.71	- 1.2	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			22	33	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 5.6 A, dl/dt = 100 A/μs, T <sub>.1</sub> = 25 °C		17	26	nC
Reverse Recovery Fall Time	t <sub>a</sub>	$F = -5.6 \text{ A}, \text{ al/at} = 100 \text{ A/}\mu\text{s}, T_{\text{J}} = 25 ^{\circ}\text{C}$		13		200
Reverse Recovery Rise Time	t <sub>b</sub>					ns

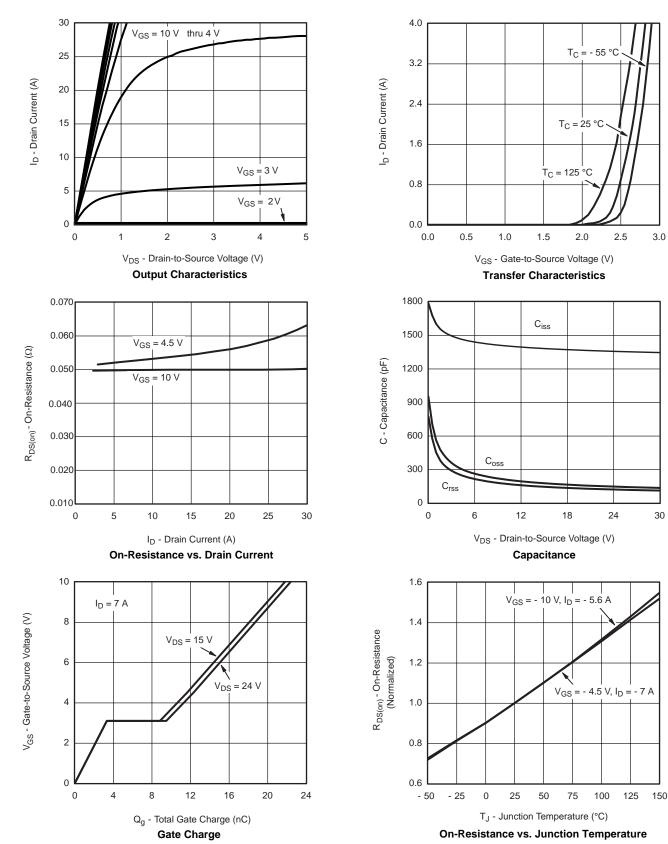
Notes:

a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

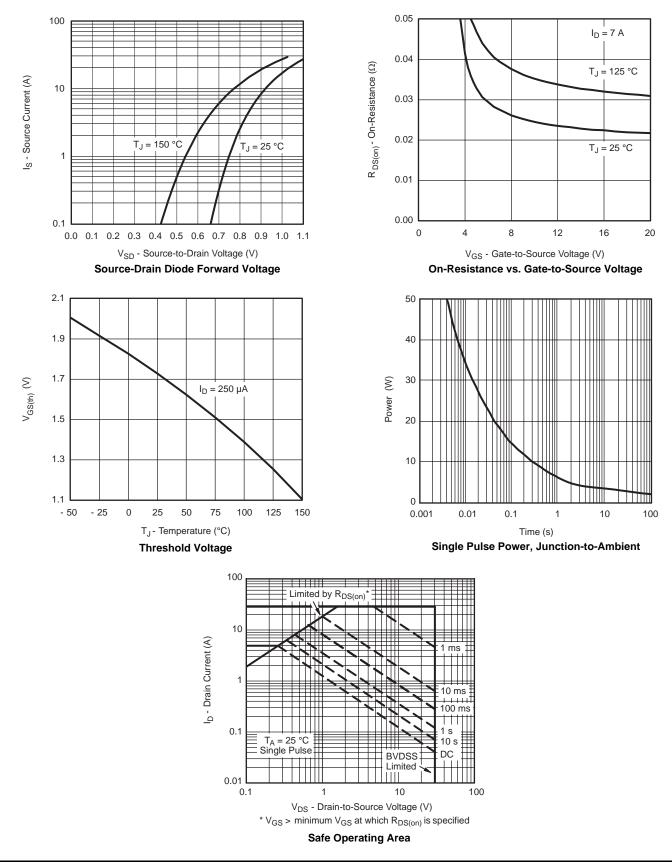
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

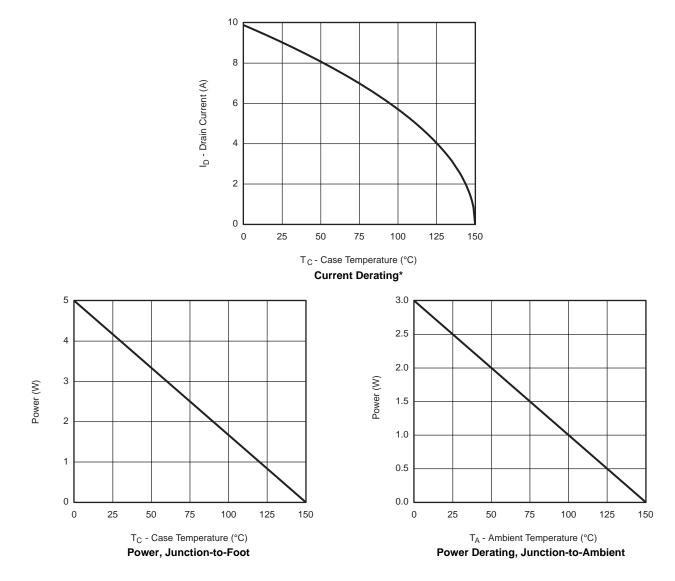




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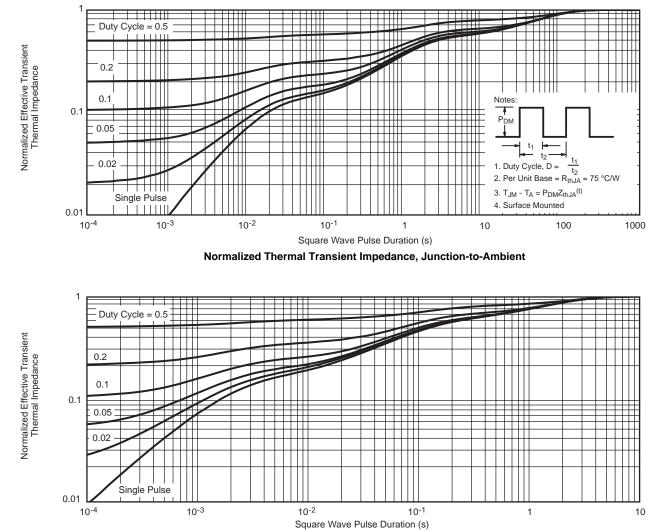
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\* The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



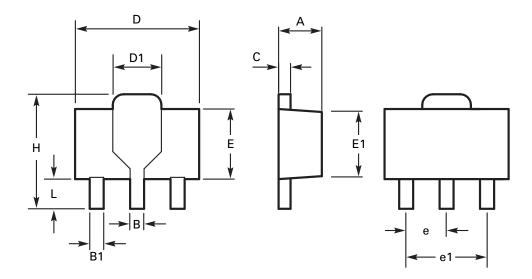




Normalized Thermal Transient Impedance, Junction-to-Foot



### Package outline - SOT89



DIM	Millim	neters	Inc	Inches DIM Millimeters Inch		Millimeters		hes	
	Min	Max	Min	Max		Min	Max	Min	Max
А	1.40	1.60	0.550	0.630	E	2.29	2.60	0.090	0.102
В	0.44	0.56	0.017	0.022	E1	2.13	2.29	0.084	0.090
B1	0.36	0.48	0.014	0.019	е	1.50 BSC		0.059 BSC	
С	0.35	0.44	0.014	0.017	e1	3.00 BSC		0.118	BSC
D	4.40	4.60	0.173	0.181	Н	3.94	4.25	0.155	0.167
D1	1.62	1.83	0.064	0.072	L	0.89	1.20	0.035	0.047

Note: Controlling dimensions are in millimeters. Approximate dimensions are provided in inches



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